adhesion of a connecting pad electrode and the like. Note that the above effects can be obtained by setting the linear expansion coefficient of the peripheral region plastic substrate to be about ⅔ or less that of the pixel region plastic substrate.

[0150] Although the pixel region plastic substrate must be transparent, the properties of organic resin make it difficult to obtain a plastic substrate having a small linear expansion coefficient such as that of inorganic glass. Hence, a plastic substrate having a large linear expansion coefficient as described above is used.

[0151] Since the linear expansion coefficient of the peripheral region plastic substrate is small, about ⅔ or less that of the pixel region plastic substrate, the linear expansion coefficients of the plastic substrate and thin glass layer are close in this peripheral region. Accordingly, the degree of expansion and contraction of this peripheral region plastic substrate when the temperature changes while the display device is in use approaches that of the thin glass layer, so no stress is applied to the thin glass layer. This raises the strength of the display device. Also, the peripheral region does not easily expand or contract even when temporarily heated and bonded by thermal compression bonding to a connecting pad electrode **110** formed in this peripheral region.

[0152] (Third Embodiment)

[0153] An active matrix type display device of the third embodiment has the characteristic features of both the first and second embodiments. That is, as shown in **FIGS. 17A and 17B**, an adhesion layer between a plastic substrate and thin glass layer is separated into a pixel region adhesion layer **1002** and peripheral region adhesion layer **1001**. In addition, the glass transition temperature of the pixel region adhesion layer **1002** is 30° C. (inclusive) to 80° C. (inclusive), and the glass transition temperature of the peripheral region adhesion layer **1001** is higher by 10° C. or more than that of the pixel region adhesion layer **1002**, and is 80° C. (exclusive) to 200° C. (inclusive).

[0154] Also, a plastic substrate is separated into a pixel region plastic substrate **1102** and a peripheral region plastic substrate **1101** formed around the pixel region plastic substrate **1102**. The linear expansion coefficient of the pixel region plastic substrate **1102** is 30 ppm/° C. (inclusive) to 300 ppm/° C. (inclusive). The linear expansion coefficient of the peripheral region plastic substrate **1101** is about 1 ppm/° C. (inclusive) to 30 ppm/° C. (exclusive), which is about ⅔ or less that of the pixel region plastic substrate **1102**. Furthermore, a slight spacing is formed between the pixel region plastic substrate **1102** and the peripheral region plastic substrate **1101**.

[0155] With this construction, the effects of both the first and second embodiments can be obtained. In addition, the materials and characteristics of both the adhesion layer and plastic substrate can be selected in the pixel region and peripheral region independently of each other. This can maintain the element characteristics more preferably and maintain the strength of the thin glass layer.

[0156] (Fourth Embodiment)

[0157] An active matrix type display device of the fourth embodiment is a modification of the second embodiment. As shown in **FIG. 18, a** portion of a peripheral region plastic substrate **1103** covers a pixel region plastic substrate **1104** to form an overlapping portion.

[0158] More specifically, the linear expansion coefficient of the pixel region plastic substrate is 30 ppm/° C. (inclusive) to 300 ppm/° C. (inclusive), and the linear expansion coefficient of the peripheral region plastic substrate is about 1 ppm/° C. (inclusive) to 30 ppm/° C. (exclusive), which is about ⅔ or less that of the pixel region plastic substrate.

[0159] Even in this embodiment, the effects of the second embodiment can be obtained. Also, the whole of a thin glass layer can be reinforced because there is no spacing between the pixel region plastic substrate **1104** and peripheral region plastic substrate **1103**.

[0160] (Fifth Embodiment)

[0161] An active matrix display device of the fifth embodiment shown in **FIG. 19** has the characteristic features of both the first and fourth embodiments. That is, an adhesion layer between a plastic substrate and thin glass layer is separated into a pixel region adhesion layer **1102** having a glass transition temperature of 30° C. (inclusive) to 80° C. (inclusive), and a peripheral region adhesion layer **1101** having a glass transition temperature which is higher by 10° C. or more than that of the pixel region adhesion layer and is 80° C. (exclusive) to 200° C. (inclusive).

[0162] Also, the plastic substrate is separated into a pixel region plastic substrate **1104** having a linear expansion coefficient of 30 ppm/° C. (inclusive) to 300 ppm/° C. (inclusive), and a peripheral region plastic substrate **1103** formed around the pixel region plastic substrate **1104** and having a linear expansion coefficient of 1 ppm/° C. (inclusive) to 30 ppm/° C. (exclusive) which is about ⅔ or less that of the pixel region plastic substrate. A portion of the peripheral region plastic substrate **1103** covers the pixel region plastic substrate **1104** to form an overlapping portion.

[0163] With this construction, the effects of both the first and fourth embodiments can be obtained. Furthermore, the materials and characteristics of both the adhesion layer and plastic substrate can be selected in the pixel region and peripheral region independently of each other. This can maintain the element characteristics more preferably and maintain the strength of the thin glass layer.

[0164] (Sixth Embodiment)

[0165] As shown in **FIGS. 20A and 20B**, an active matrix type display device of the sixth embodiment differs from the first embodiment in that a substrate on which a common electrode **205** is formed comprises only a plastic substrate **501** with no thin glass layer. This configuration can reduce the number of manufacturing steps and can also reduce readily breakable regions, in addition to the effects of the first embodiment.

[0166] A method of manufacturing the active matrix type display device of this embodiment will be explained below with reference to FIGS. **21** to **29**A and **29**B.

[0167] As in the first embodiment, an element circuit region **102** and connecting pad electrode **110** are formed on a first non-alkaline glass substrate **201**. After that, as shown in **FIG. 21**, this first non-alkaline glass substrate **201** having the element circuit region **102** and connecting pad electrode